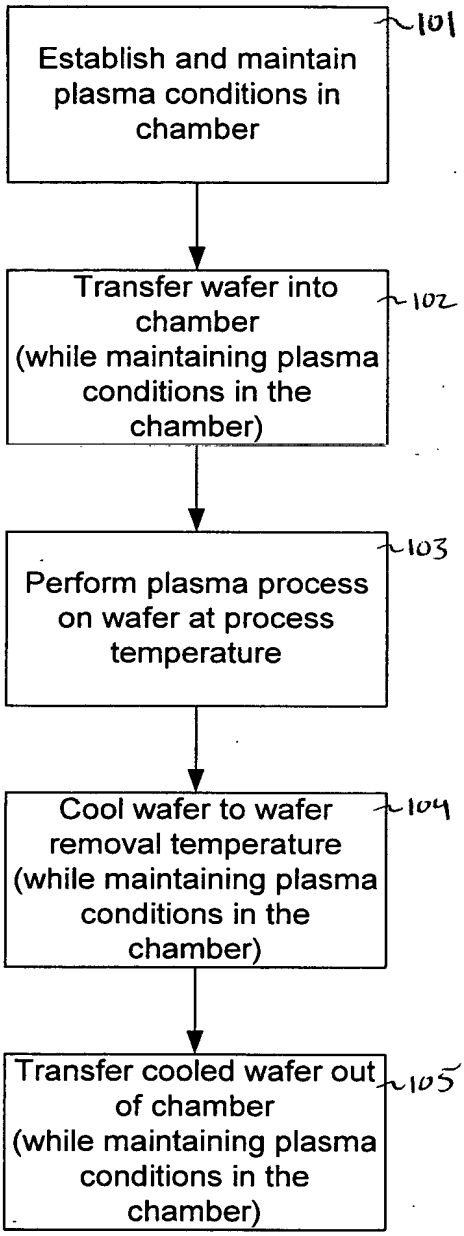
Establish and maintain plasma conditions in chamber
101
Transfer wafer into chamber (while maintaining plasma conditions in the chamber)
102
Perform plasma process on wafer at process temperature
103
Cool wafer to wafer removal temperature (while maintaining plasma conditions in the chamber)
104
Transfer cooled wafer out of chamber (while maintaining plasma conditions in the chamber)
105

Figure 1